Smart Manufacturing Networks for Industry 4.0

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Message from the Guest Editors

Smart Manufacturing Networks for Industry 4.0 namely the integration of both the physical and virtual network world, is the trend of the global development era of production manufacturing. Effectively strengthening and improving the efficiency and performance of Smart Manufacturing Networks for Industry 4.0 by reinforcing operational reliability and deepening the interaction between humans and machines is crucial and is a top priority.

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Special issue

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Message from the Editor-in-Chief

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